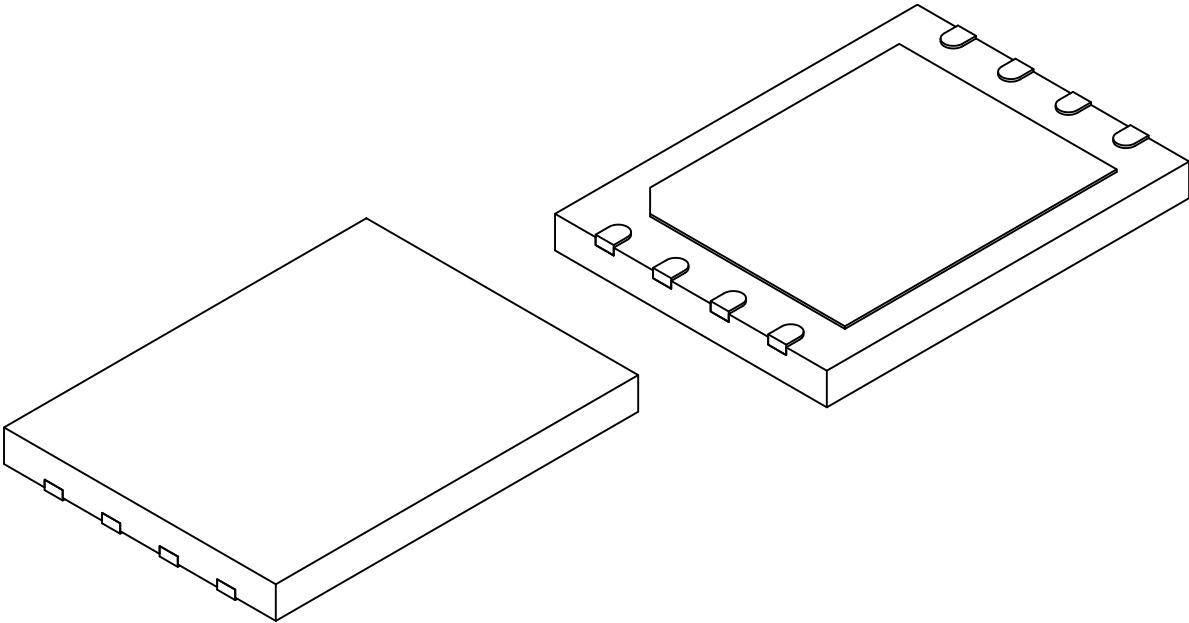


8-Lead Very, Very Thin Small Outline No-Lead (MN) - 8x6x0.8 mm Body [WSON]
(Also Called WDFN)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	0.70	0.75	0.80
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.20 REF		
Overall Width	D	8.00 BSC		
Exposed Pad Width	D2	5.90	6.00	6.10
Overall Length	E	6.00 BSC		
Exposed Pad Length	E2	4.70	4.80	4.90
Terminal Width	b	0.35	0.45	0.50
Terminal Length	L	0.45	0.50	0.55
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

- 1. The Pin 1 visual index feature may vary, but it must be located within the hatched area.
- 2. The package is saw singulated.
- 3. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
 - REF: Reference Dimension, usually without tolerances, is for information purposes only.